



**PARA LIGHT ELECTRONICS CO., LTD.**

4F, No.1, Lane 93, Chien Yi Road, Chung Ho City, Taipei, Taiwan, R.O.C.

Tel: 886-2-2225-3733

Fax: 886-2-2225-4800

E-mail: [para@para.com.tw](mailto:para@para.com.tw)

<http://www.para.com.tw>

**DATA SHEET**

**PART NO. : L-314GD**

**REV : A / 1**

CUSTOMER'S APPROVAL : \_\_\_\_\_

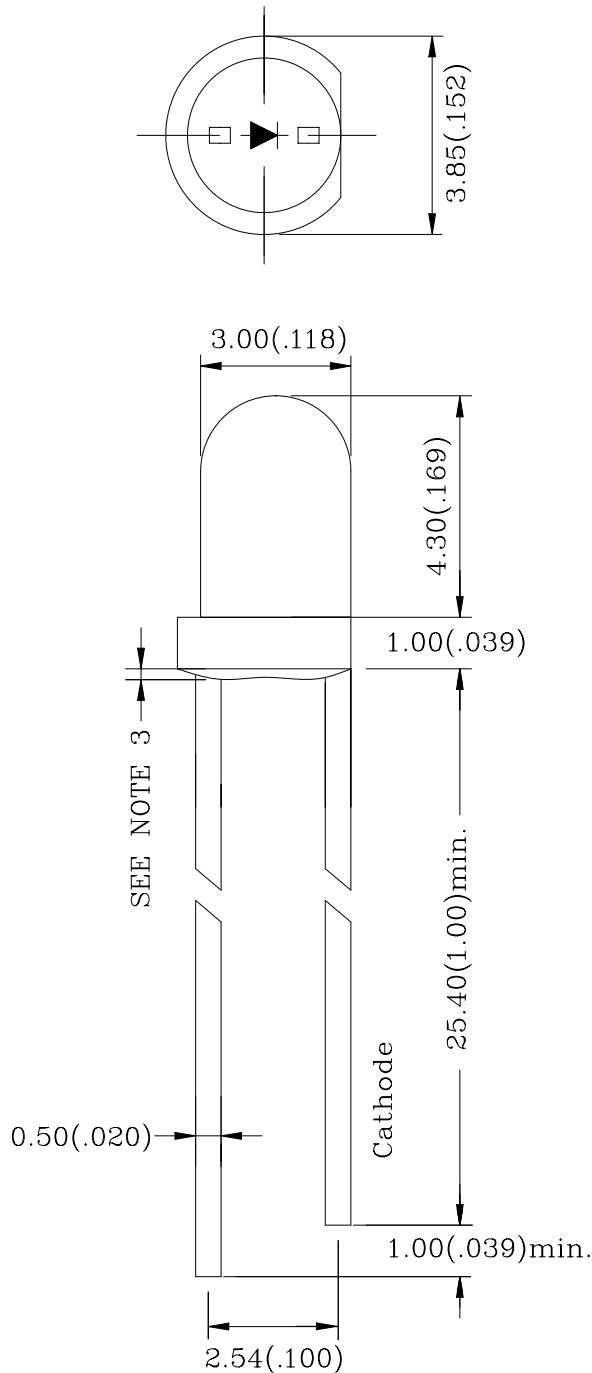
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PACKAGE DIMENSIONS



Note:

1. All Dimensions are in millimeters.
2. Tolerance is  $\pm 0.25\text{mm}$  (0.010 ") Unless otherwise specified.
3. Protruded resin under flange is 1.5mm (0.059 ") max.
4. Lead spacing is measured where the leads emerge from the package.
5. Specification are subject to change without notice

## FEATURES

- \* 3.0mm DIA LED LAMP
- \* LOW POWER CONSUMPTION.
- \* I.C. COMPATIBLE.
- \* LONG LIFE SOLID STATE RELIABILITY.

## CHIP MATERIALS

- \* Dice Material : GaP/GaP
- \* Light Color : YELLOW GREEN
- \* Lens Color : GREEN DIFFUSED

## ABSOLUTE MAXIMUM RATING : ( Ta = 25°C )

SYMBOL	PARAMETER	YELLOW GREEN	UNIT
PAD	Power Dissipation Per Chip	85	mW
VR	Reverse Voltage Per Chip	5	V
IAF	Continuous Forward Current Per Chip	30	mA
IPF	Peak Forward Current Per Chip (Duty – 0.1,1KHz)	120	mA
—	Derating Linear From 25°C Per Chip	0.40	mA/°C
Topr	Operating Temperature Range	-25°C to 85°C	
Tstg	Storage Temperature Range	-40°C to 85°C	
Lead Soldering Temperature { 1.6mm(0.063 inch) From Body } 250°C ± 5°C for 3 Seconds			

## ELECTRO-OPTICAL CHARACTERISTICS : ( Ta = 25°C )

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
VF	Forward Voltage	IF = 20mA		2.2	2.8	V
IR	Reverse Current	VR = 5V			100	μA
λD	Dominant Wavelength	IF = 20mA		570		nm
Δλ	Spectral Line Half - Width	IF = 20mA		30		nm
2θ1/2	Half Intensity Angle	IF = 20mA		60		deg
IV	Luminous Intensity	IF = 20mA		20		mcd